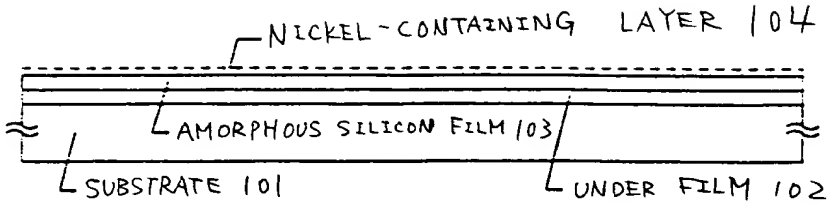


Fig. 1A

LASER CRYSTALLIZATION STEP

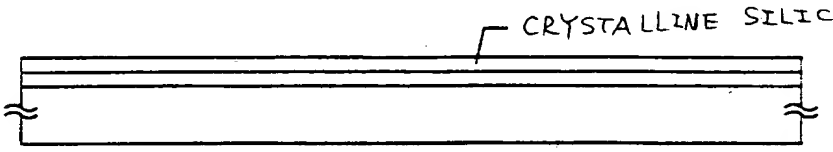


Fig. 1B

THERMAL TREATMENT STEP IN REDUCING ATMOSPHERE

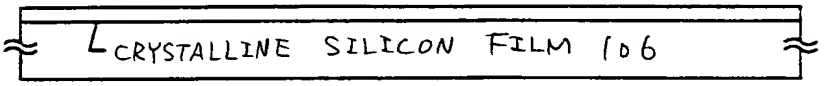


Fig. 1C

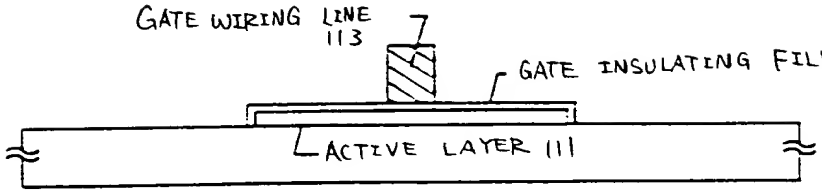


Fig. 2A

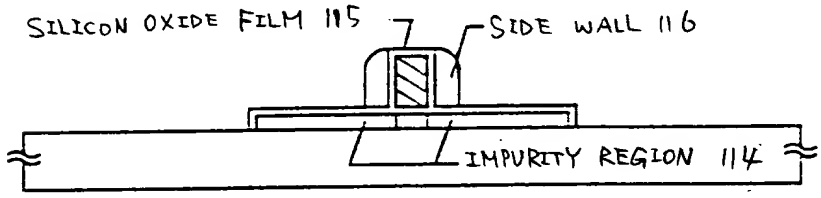


Fig. 2B

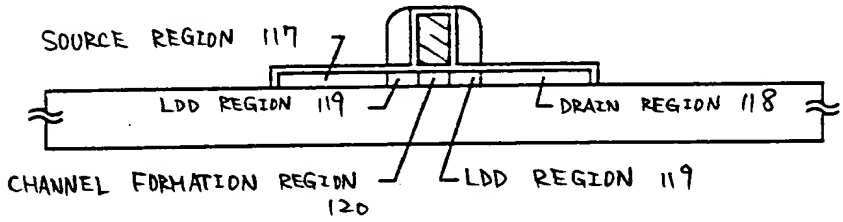


Fig. 2C

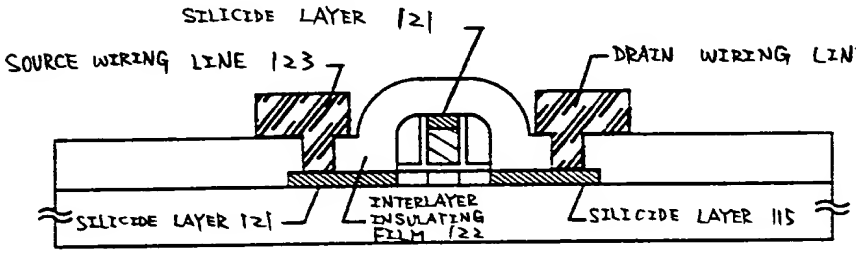


Fig. 2D

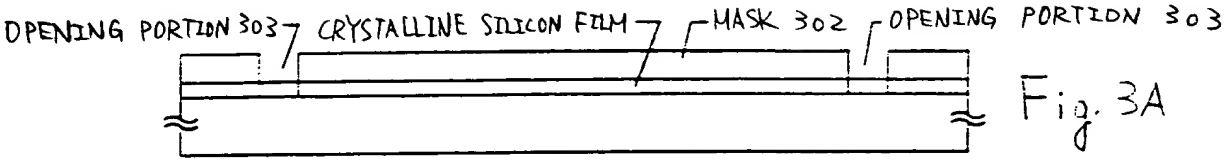


Fig. 3A

ADDING STEP OF PHOSPHORUS

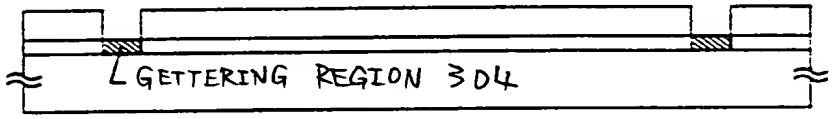


Fig. 3B

GETTERING STEP

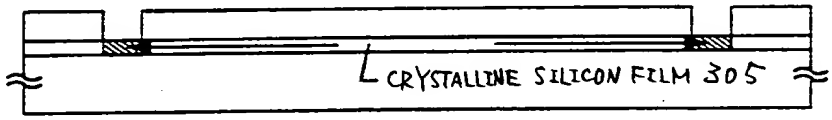


Fig. 3C

HEAT TREATMENT STEP IN REDUCING ATMOSPHERE

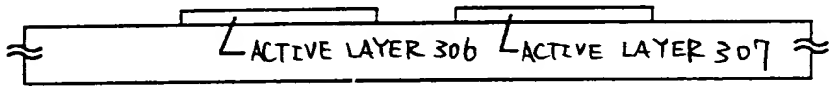


Fig. 3D

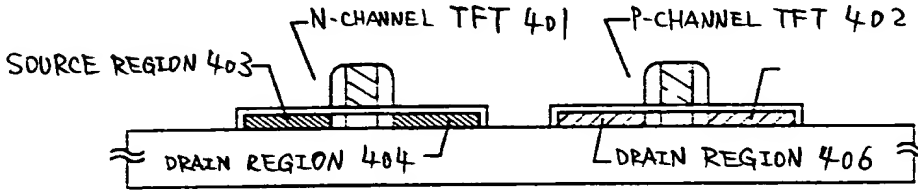


Fig. 4A

GETTERING STEP

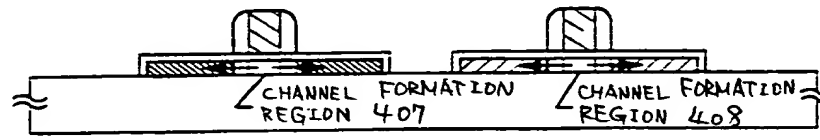


Fig. 4B

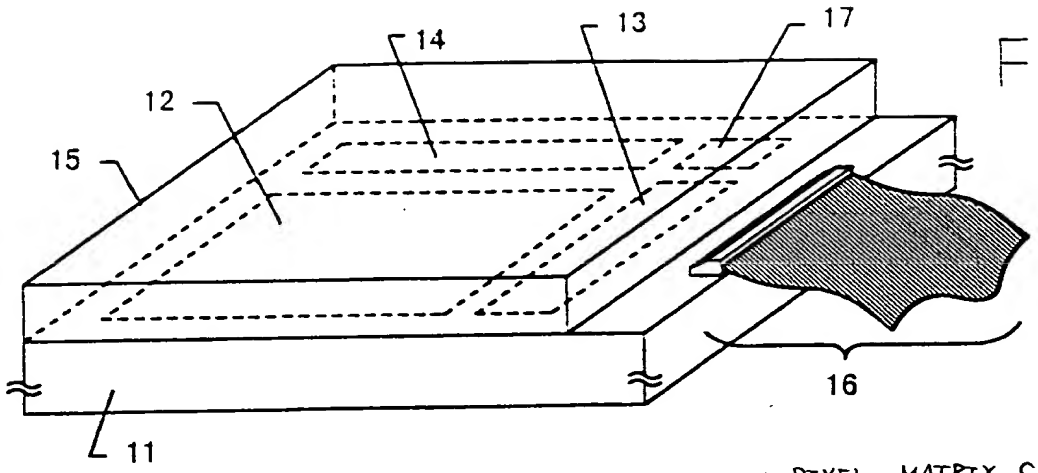


Fig. 5A

11 : SUBSTRATE HAVING INSULATING SURFACE 12 : PIXEL MATRIX CIRCUIT
13 : SOURCE DRIVER CIRCUIT 14 : GATE DRIVER CIRCUIT
15 : OPPOSITE SUBSTRATE 16 : FPC
17 : SIGNAL PROCESSING CIRCUIT

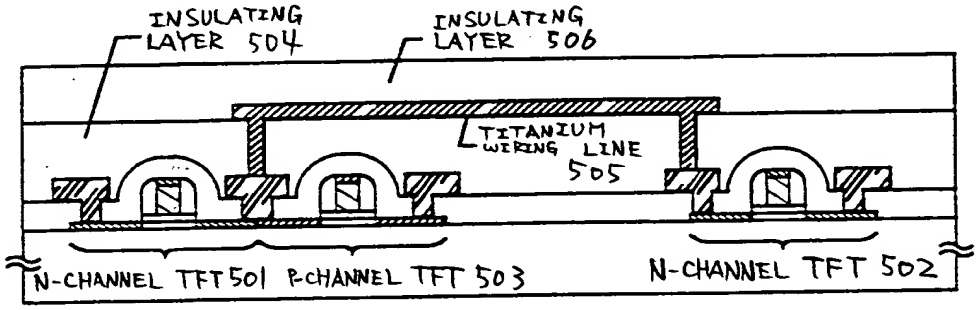


Fig. 5B

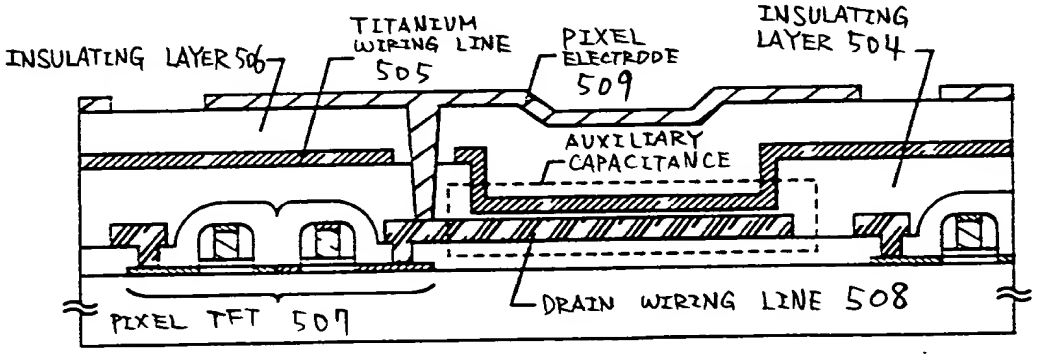


Fig. 5C

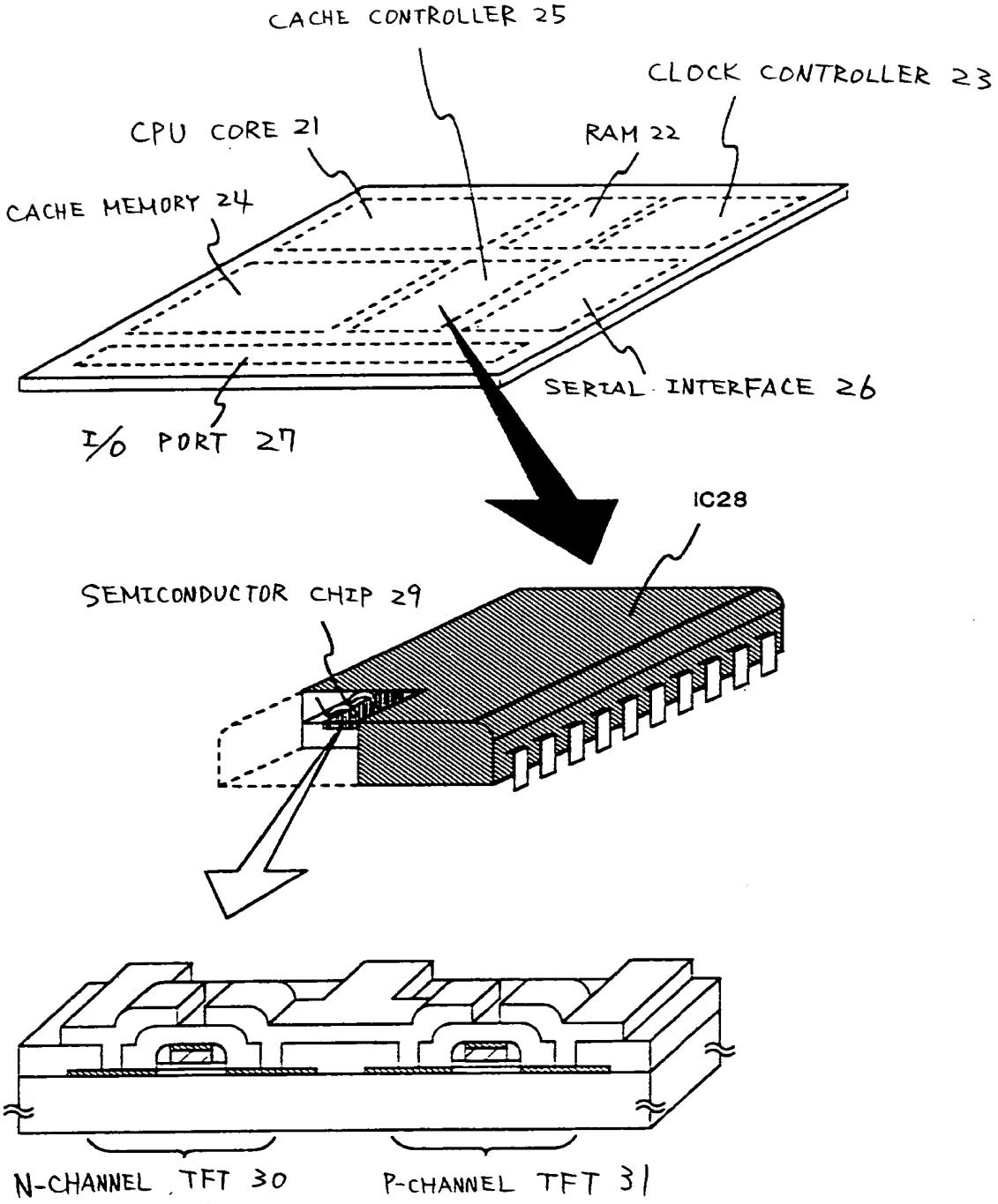
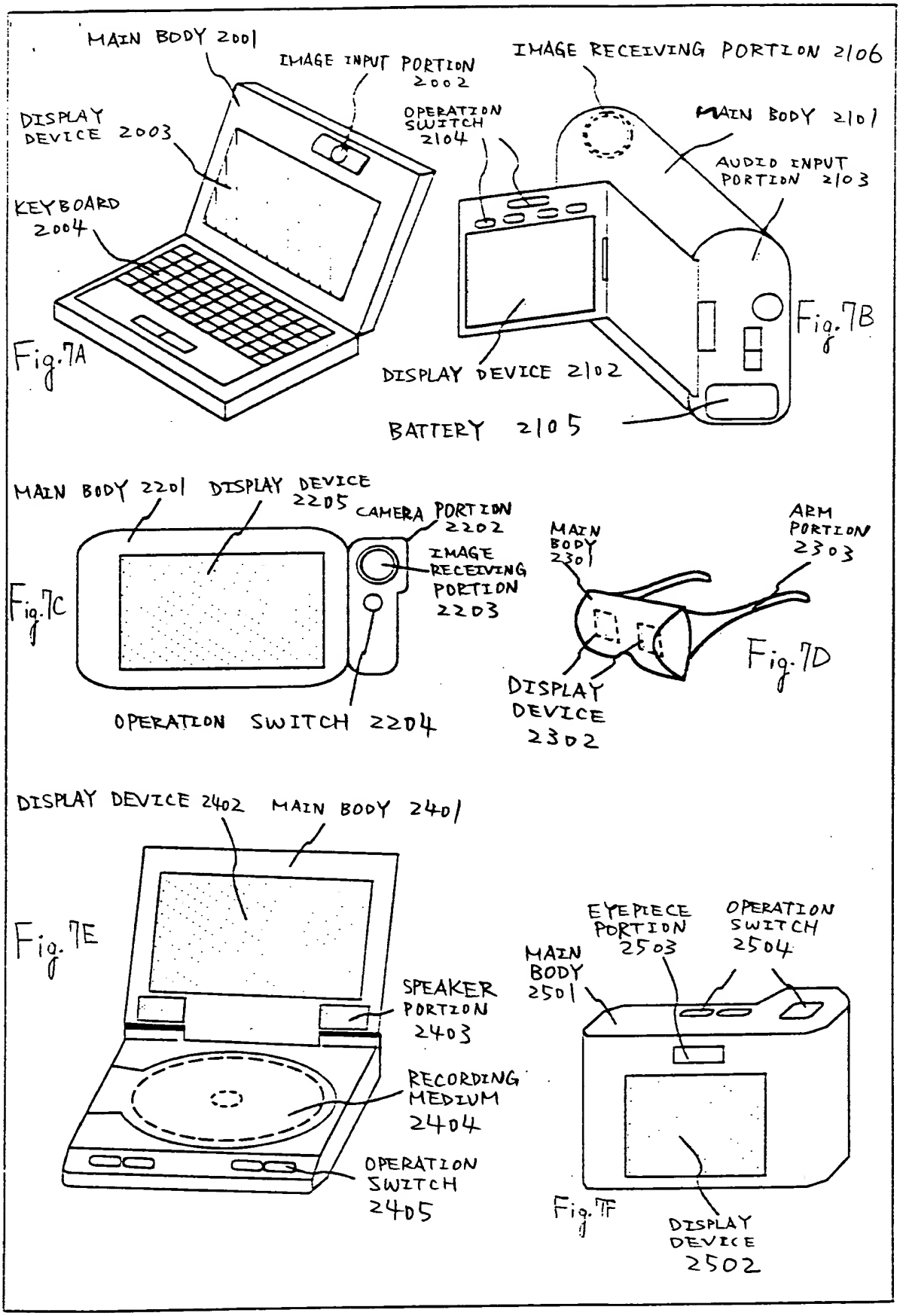

CACHE CONTROLLER 25
CLOCK CONTROLLER 23
CPU CORE 21
RAM 22
CACHE MEMORY 24
SERIAL INTERFACE 26
I/O PORT 27
IC28
SEMICONDUCTOR CHIP 29
N-CHANNEL TFT 30
P-CHANNEL TFT 31

Fig. 6


MAIN BODY 2001
IMAGE INPUT PORTION 2002
DISPLAY DEVICE 2003
KEYBOARD 2004
Fig. 7A
IMAGE RECEIVING PORTION 2106
OPERATION SWITCH 2104
MAIN BODY 2101
AUDIO INPUT PORTION 2103
Fig. 7B
DISPLAY DEVICE 2102
BATTERY 2105
MAIN BODY 2201
DISPLAY DEVICE 2205
CAMERA PORTION 2202
IMAGE RECEIVING PORTION 2203
Fig. 7C
OPERATION SWITCH 2204
MAIN BODY 2301
ARM PORTION 2303
Fig. 7D
DISPLAY DEVICE 2302
DISPLAY DEVICE 2402
MAIN BODY 2401
Fig. 7E
SPEAKER PORTION 2403
RECORDING MEDIUM 2404
OPERATION SWITCH 2405
EYEPIECE PORTION 2503
OPERATION SWITCH 2504
MAIN BODY 2501
Fig. 7F
DISPLAY DEVICE 2502

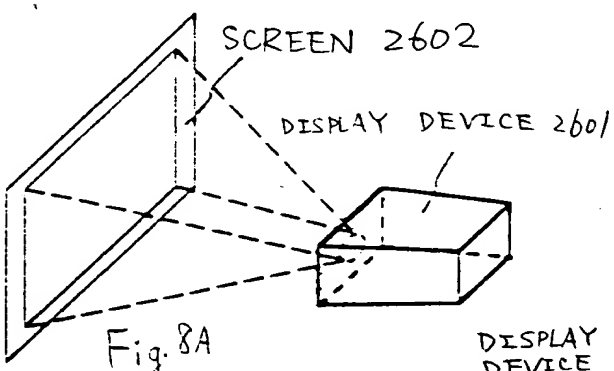


Fig. 8A

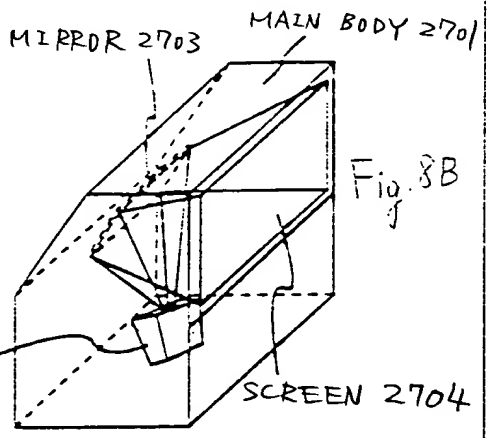


Fig. 8B

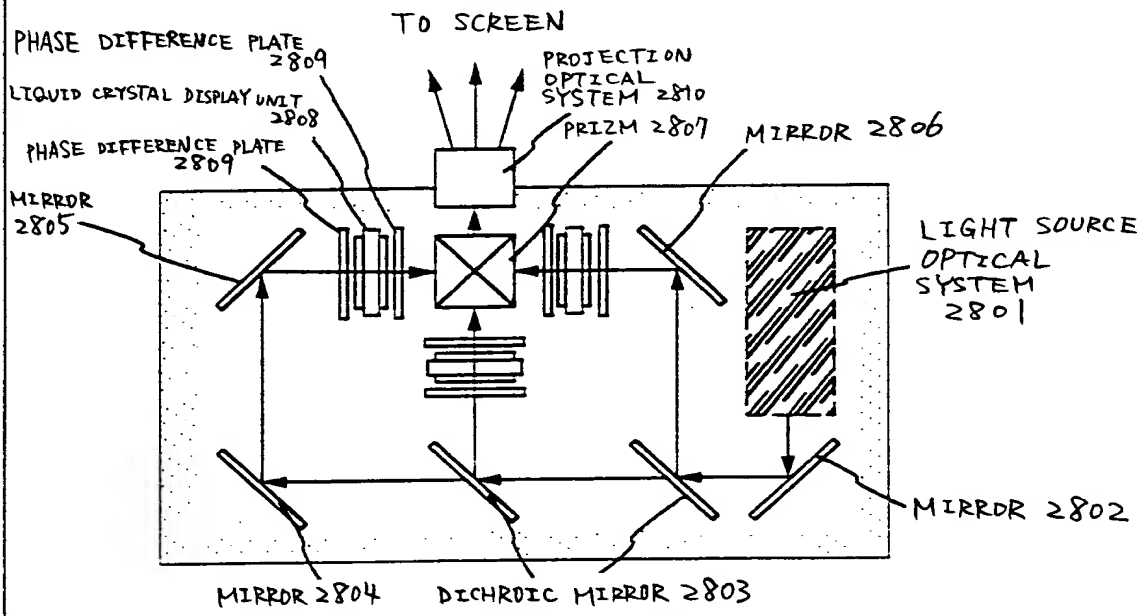


Fig. 8C DISPLAY DEVICE (THREE-PLATE TYPE)

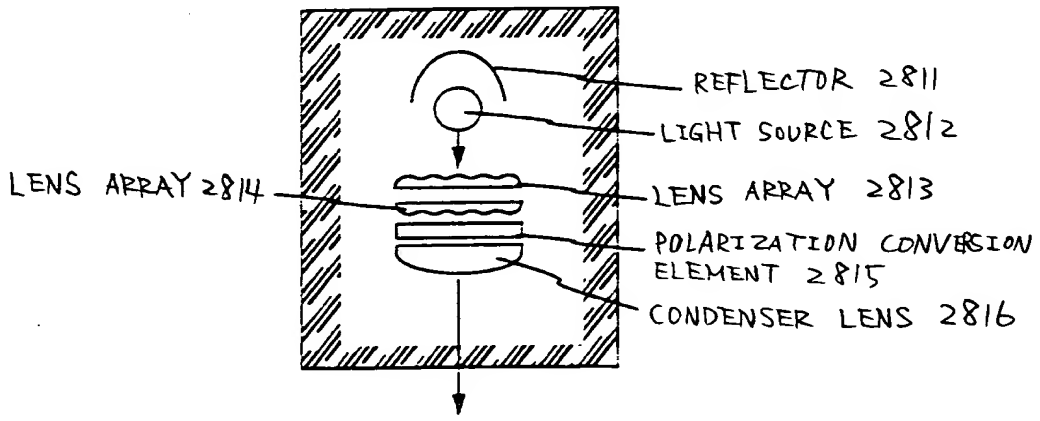


Fig. 8D LIGHT SOURCE OPTICAL SYSTEM

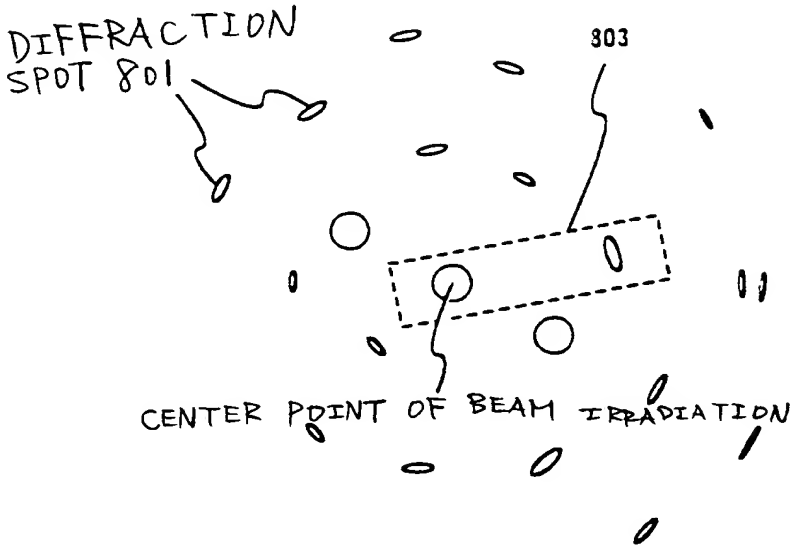

DIFFRACTION SPOT 801
303
CENTER POINT OF BEAM IRRADIATION AREA 802

Fig. 9A

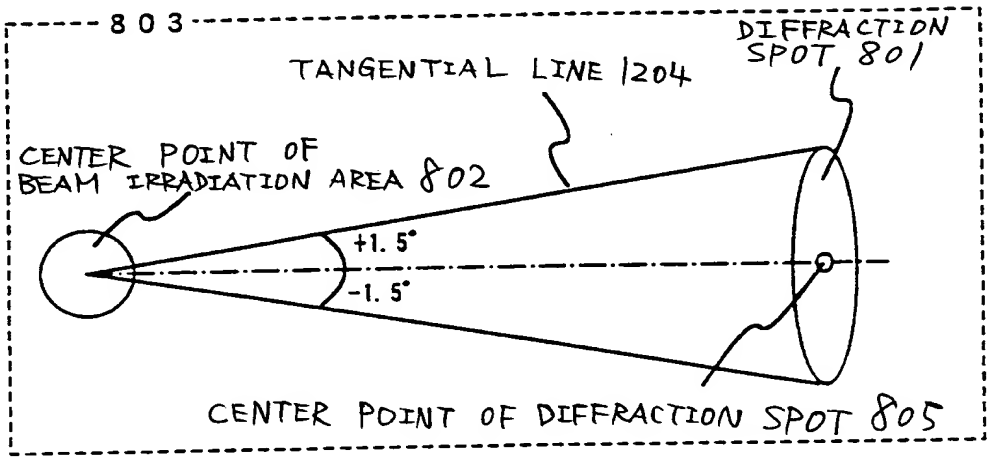

803
DIFFRACTION SPOT 801
TANGENTIAL LINE 1204
CENTER POINT OF BEAM IRRADIATION AREA 802
+1.5°
-1.5°
CENTER POINT OF DIFFRACTION SPOT 805

Fig. 9B

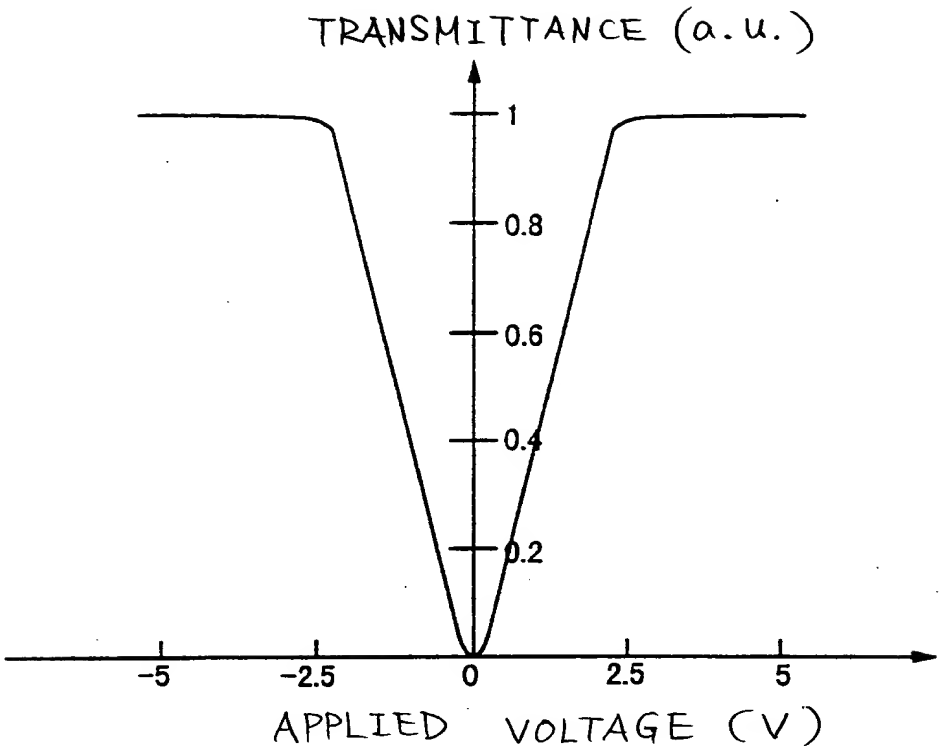


Fig.10

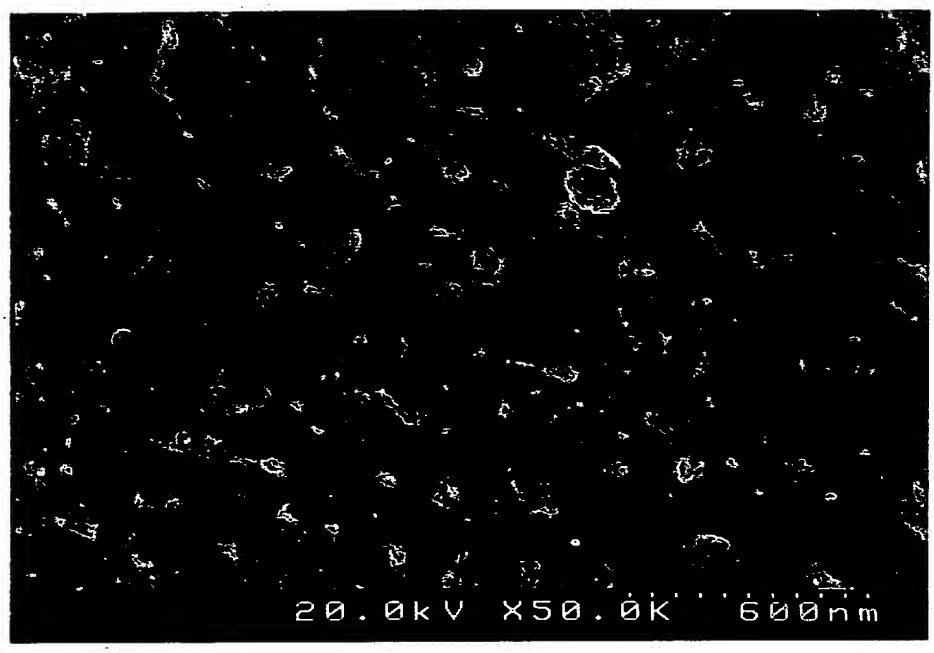


Fig.11

BEFORE HIGH TEMPERATURE ANNEALING

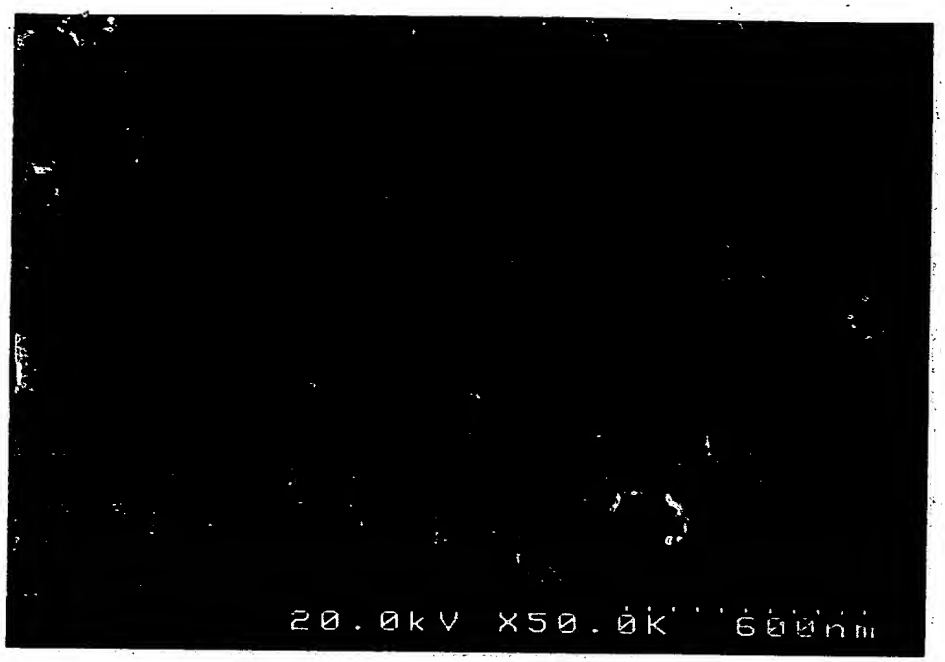


Fig. 12

AFTER HIGH TEMPERATURE ANNEALING

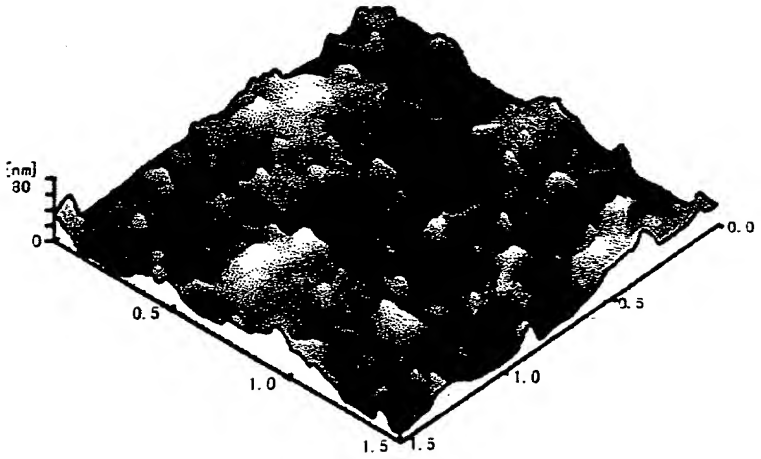


Fig. 13

BEFORE HIGH TEMPERATURE ANNEALING

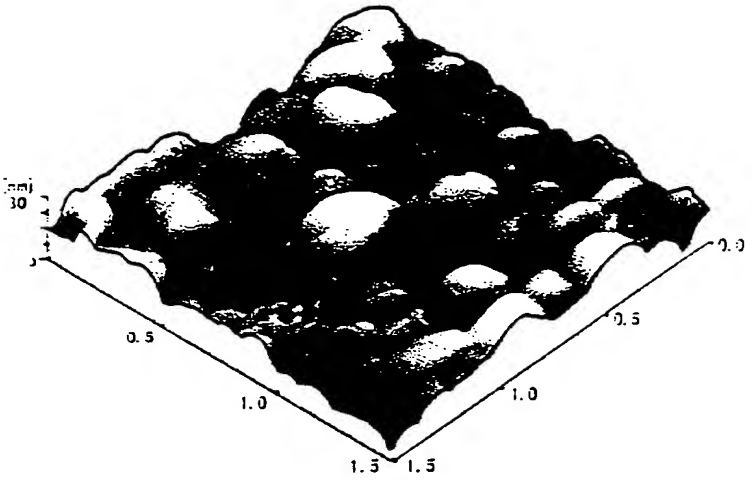


Fig. 14

AFTER HIGH TEMPERATURE ANNEALING

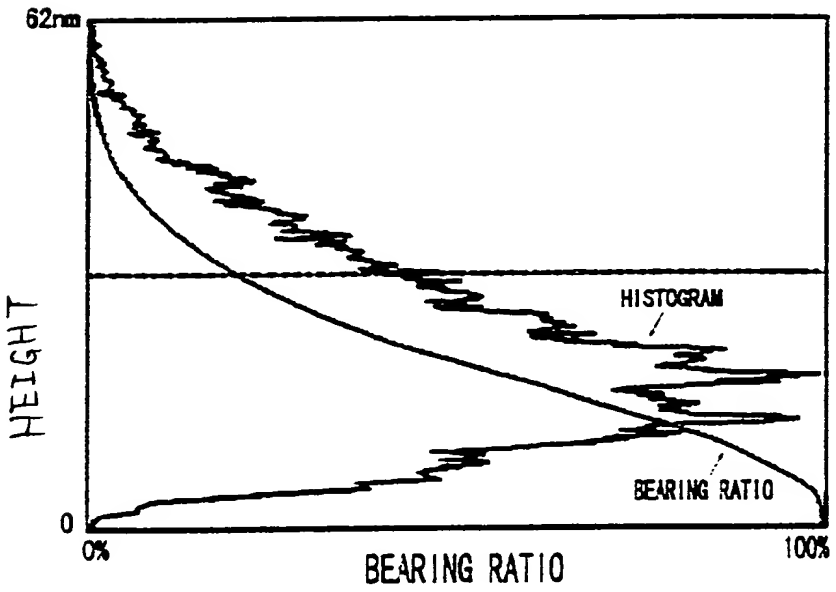


Fig. 15

BEFORE HIGH TEMPERATURE ANNEALING

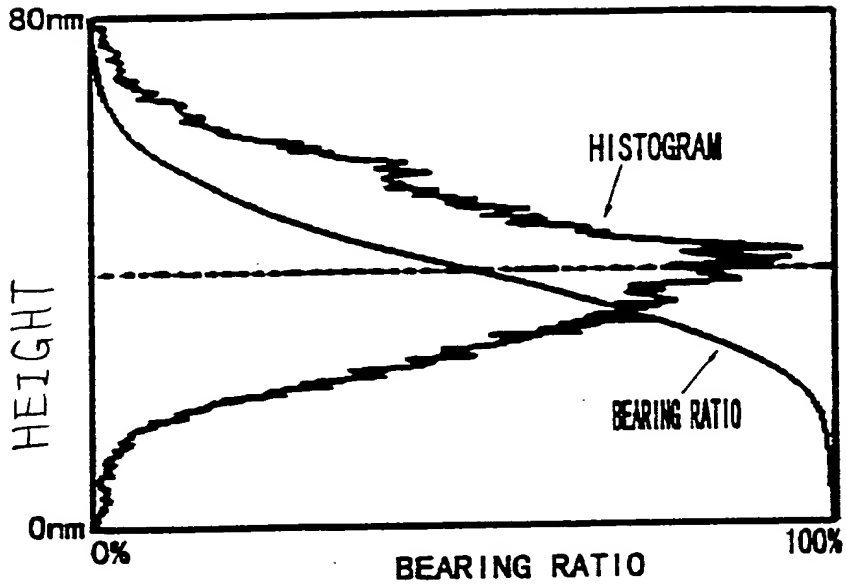


Fig.16

AFTER HIGH TEMPERATURE ANNEALING

OBSERVATION REGION	BEFORE HIGH TEMPERATURE ANNEALING	AFTER HIGH TEMPERATURE ANNEALING
1	13.623	40.925
2	20.027	51.126
3	20.629	59.364
4	21.798	48.539
5	16.666	55.341
6	15.097	46.510
7	13.120	57.655
8	14.035	51.120
9	12.599	54.416
10	20.699	36.945
MINIMUM VALUE (%)	12.60	36.95
MAXIMUM VALUE (%)	21.80	59.36
AVERAGE VALUE (%)	16.83	50.19
STANDARD DEVIATION σ	3.61	7.18

Fig.17

BEARING RATIO AT 2^{-1}(P-V VALUE) (%)